

SLU SERIES

8 to 15kV, 450 to 850mA, 40 to 50nS Surface Mount Diodes



Features

- Long Surface Mount Package
- J Lead or Gullwing Package Option
- Available in Cut Tape and 1000 Piece Reels
- Molded Plastic Body, ANSI/UL94 V-0 Rated Material

Specifications¹

Part Number	V _{RRM} V	I _{FAVM1} 2 mA	I _{FAVM2} 2 mA	I _{FAVM3} ² mA	V _F V	l _R μΑ	I _{FSM}	C _J pF	T _{RR} ² nS	R _{θJL} °C/W	R _{θJC} °C/W
J Lead Subseries (Figure 1)											
SLU08M	8000	850	450	400	12	0.5	20	7.5	40	13	20
SLU15M	15000	450	250	240	16	0.5	20	3.5	50	13	20
Gullwing Subseries (Figure 2)											
SLU08MG	8000	850	450	400	12	0.5	20	7.5	40	13	20
SLU15MG	15000	450	250	240	16	0.5	20	3.5	50	13	20

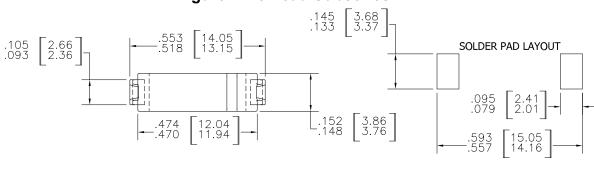
Temperature °C					
Operating Temperature	-55 to 150				
Storage Temperature	-55 to 175				
Maximum Junction Temperature	150				

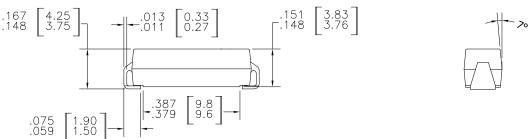
¹25°C ambient temperature unless stated otherwise.

Drawings

Dimensions in inches [mm], tolerances ±0.020 except as noted

Figure 1 – J Lead Subseries





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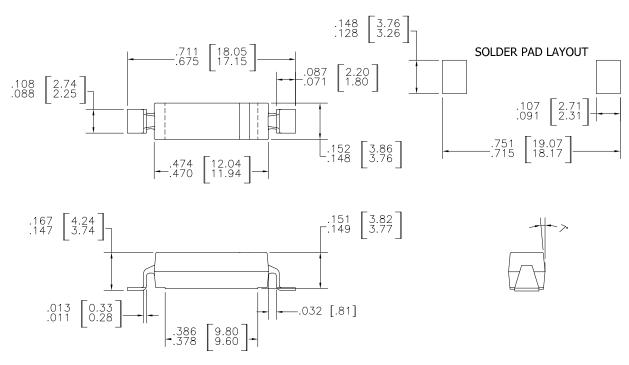
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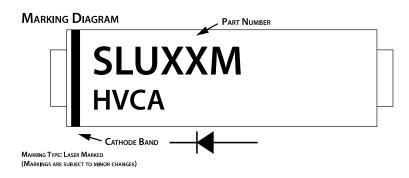
²Check Specification Definitions for conditions details.

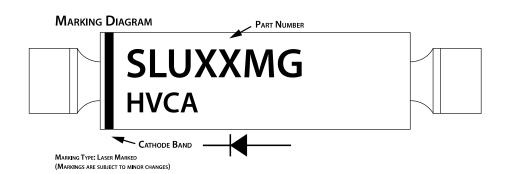


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Figure 2 – Gullwing Subseries







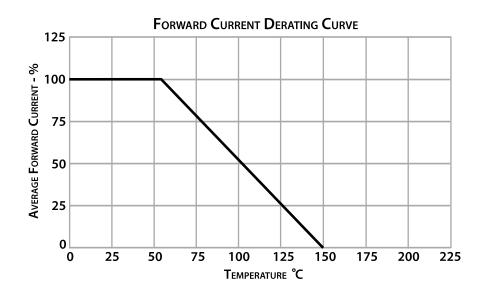
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Specification Definitions

	Specifications	Conditions
V_{RRM}	Maximum Repetitive Reverse Voltage	-
I _{FAVM1}	Maximum Average Forward Current	At T _L = 55°C
I _{FAVM2}	Maximum Average Forward Current	At $T_L = 100$ °C
I _{FAVM3}	Maximum Average Forward Current	At $T_C = 80$ °C
V _F	Maximum Forward Voltage Drop	At 100mA
I_R	Maximum Leakage Current	At V _{RRM}
I _{FSM}	Maximum Surge Current	At 8.3 mS, Single Half Sine
CJ	Typical Junction Capacitance	At $V_R = 0VDC$, $f = 1MHz$
T _{RR}	Maximum Reverse Recovery Time	I_F = 250mA; I_R = -500mA; I_{RR} = -125mA (SLU08M, SLU08MG) I_F = 100mA; I_R = -200mA; I_{RR} = -50mA (SLU15M, SLU15MG)
$R_{\theta JL}$	Typical Thermal Resistance Junction to Lead	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads
R _{θJC}	Typical Thermal Resistance Junction to Case	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads

ROHS

Note: Specifications subject to change without notice. Photo is representation only.

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